

# COS/MOS INTEGRATED CIRCUIT

4041UB

HCC/HCF 4041UB

## QUAD TRUE/COMPLEMENT BUFFER

- BALANCED SINK AND SOURCE CURRENT; APPROXIMATELY 4 TIMES STANDARD "B" DRIVE
- EQUALIZED DELAY TO TRUE AND COMPLEMENT OUTPUTS
- QUIESCENT CURRENT SPECIFIED TO 20V FOR HCC DEVICE
- 5V, 10V AND 15V PARAMETRIC RATINGS
- INPUT CURRENT OF 100 nA AT 18V AND 25°C FOR HCC DEVICE
- 100% TESTED FOR QUIESCENT CURRENT
- MEETS ALL REQUIREMENTS OF JEDEC TENTATIVE STANDARD NO. 13A, "STANDARD SPECIFICATIONS FOR DESCRIPTION OF "B" SERIES CMOS DEVICES"

The **HCC 4041 UB** (extended temperature range) and **HCF 4041 UB** (intermediate temperature range) are monolithic integrated circuits, available in 14-lead dual in-line plastic or ceramic package, ceramic flat package and plastic micropackage.

The **HCC/HCF 4041 UB** types are quad true/complement buffers consisting of n- and p-channel units having low channel resistance and high current (sourcing and sinking) capability. The **HCC/HCF 4041 UB** is intended for use as a buffer, line driver, or COS/MOS-to-TTL driver. It can be used as an ultra-low power resistor-network driver for A/D and D/A conversion, as a transmission-line driver, and in other applications where high noise immunity and low-power dissipation are primary design requirements.

## ABSOLUTE MAXIMUM RATINGS

$V_{DD}^*$	Supply voltage: <b>HCC</b> types <b>HCF</b> types	-0.5 to 20 -0.5 to 18	V V
$V_i$	Input voltage	-0.5 to $V_{DD} + 0.5$	V
$I_i$	DC input current (any one input)	$\pm 10$	mA
$P_{tot}$	Total power dissipation (per package)	200	mW
	Dissipation per output transistor for $T_{op}$ = full package-temperature range	100	mW
$T_{op}$	Operating temperature: <b>HCC</b> types <b>HCF</b> types	-55 to 125 -40 to 85	°C °C
$T_{stg}$	Storage temperature	-65 to 150	°C

\* All voltage values are referred to  $V_{SS}$  pin voltage

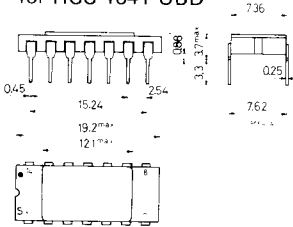
## ORDERING NUMBERS:

- HCC 4041 UBD for dual in-line ceramic package
- HCC 4041 UBF for dual in-line ceramic package, frit seal
- HCC 4041 UBK for ceramic flat package
- HCF 4041 UBE for dual in-line plastic package
- HCF 4041 UBF for dual in-line ceramic package, frit-seal
- HCF 4041 UBM for plastic micropackage

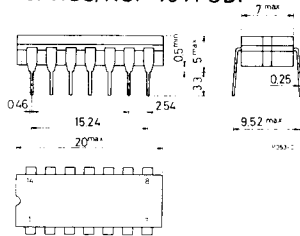
# HCC/DCF 4041 UB

## MECHANICAL DATA (dimensions in mm)

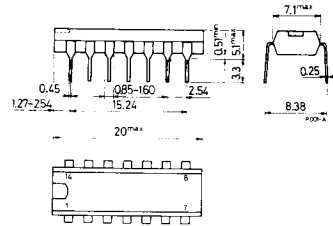
Dual in-line ceramic package for HCC 4041 UBD



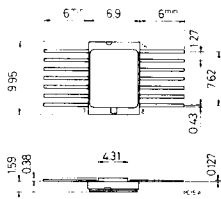
Dual in-line ceramic package for HCC/DCF 4041 UBF



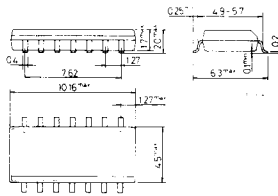
Dual in-line plastic package for HCF 4041 UBE



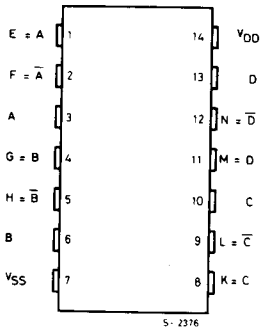
Ceramic flat package for HCC 4041 UBK



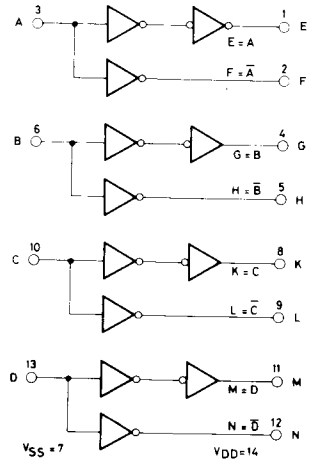
Plastic micropackage for HCF 4041 UBM



## CONNECTION DIAGRAM

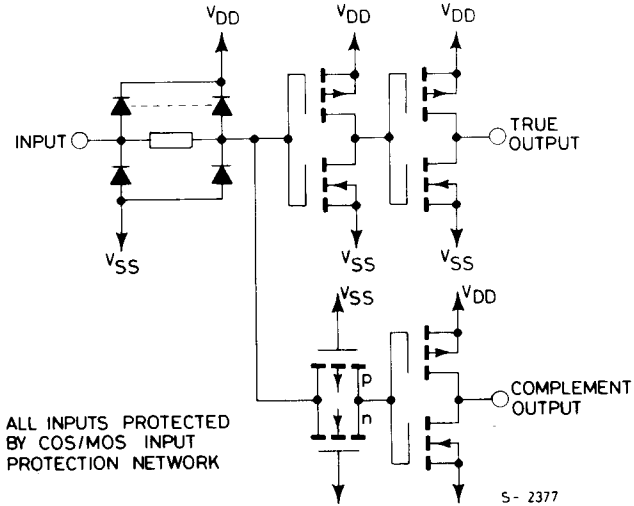


## FUNCTIONAL DIAGRAM



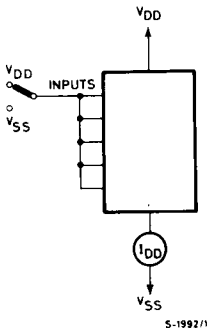
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SCHEMATIC DIAGRAM

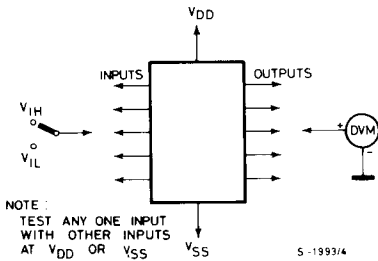


TEST CIRCUITS

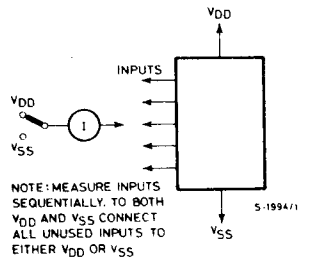
Quiescent device current



Noise immunity



Input leakage current



RECOMMENDED OPERATING CONDITIONS

$V_{DD}$	Supply voltage: HCC types HCF types	3 to 18 V 3 to 15 V
$V_I$	Input voltage	0 to $V_{DD}$ V
$T_{op}$	Operating temperature: HCC types HCF types	-55 to 125 °C -40 to 85 °C

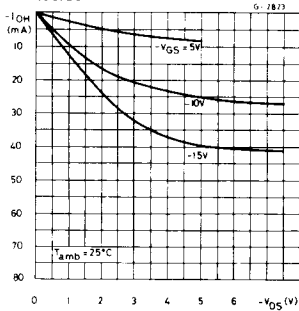


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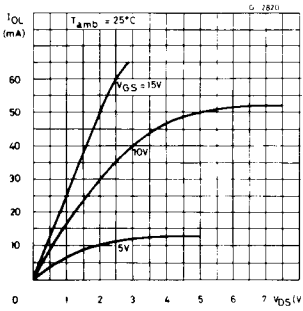
**DYNAMIC ELECTRICAL CHARACTERISTICS** ( $T_{amb} = 25^{\circ}\text{C}$ ,  $C_L = 50\text{ pF}$ ,  $R_L = 200\text{ k}\Omega$ , typical temperature coefficient for all  $V_{DD}$  values is  $0.3\%/^{\circ}\text{C}$ , all input rise and fall times =  $20\text{ ns}$ )

Parameter	Test conditions	Values			Unit	
		$V_{DD}$ (V)	Min.	Typ.		Max.
$t_{PLH}$ , $t_{PHL}$ Propagation delay time		5		60	120	ns
		10		35	70	
		15		25	50	
$t_{THL}$ , $t_{TLH}$ Transition time		5		40	80	ns
		10		20	40	
		15		15	30	

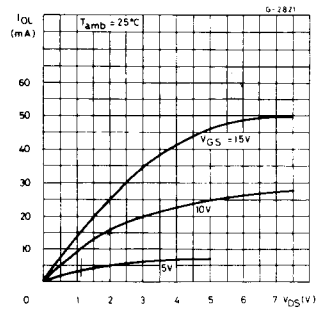
Minimum output high (source) current characteristics



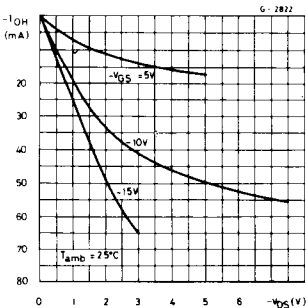
Typical output low (sink) current



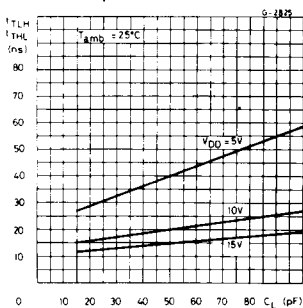
Minimum output low (sink) current characteristics



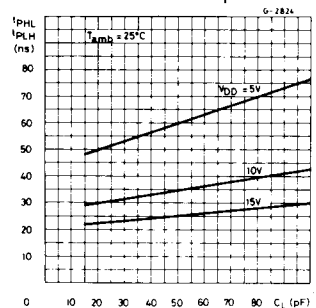
Typical output high (source) current characteristics



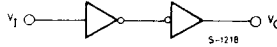
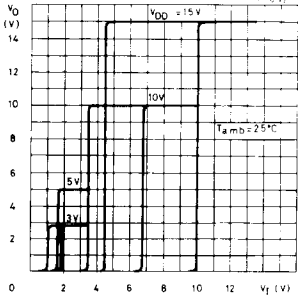
Typical transition time vs. load capacitance



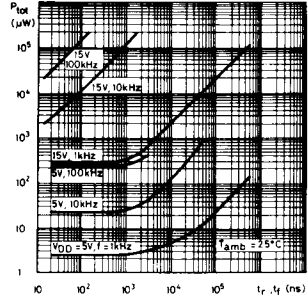
Typical propagation delay time vs. load capacitance



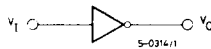
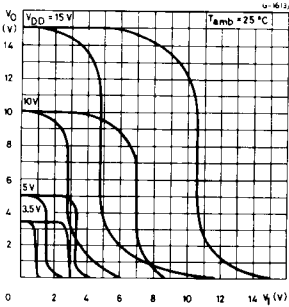
Minimum and maximum transfer characteristics—true output—and test circuit



Typical power dissipation vs. input rise and fall time per output pair



Minimum maximum transfer characteristics—complement output—and test circuit



Typical power dissipation vs. frequency per output pair

